

HEATER FOR BONDING APPARATUS AND METHOD OF COOLING THE SAME

ABSTRACT

Provided is a plate-like heater for a bonding apparatus (30) including: a lower surface (31b) to which a bonding tool (40) is attached; and an upper surface (31a) to which a heat insulator (20) is attached. The upper surface (31a) is provided with a large number of capillary slits (35), and the large number of capillary slits (35) and a matching surface (21) of the heat insulator (20) attached to the upper surface (31a) form a large number of capillary coolant flow-paths (37) each extending from a cavity (36) to a lateral surface (33). This allows effective cooling of the heater for a bonding apparatus.

FIGURE 1